



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kie Y. Ahn et al.

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Docket No.: 303.672US1

Serial No.: 09/483881

Filed: January 18, 2000

Due Date: N/A

Examiner: Ha Nguyen

Group Art Unit: 2812

Customer No.: 21186

Confirmation No.: 8976

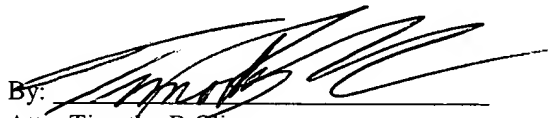
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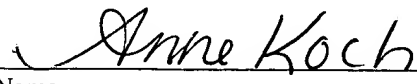
- ☒ A return postcard.
- ☒ An Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (7 pgs.), and copies of 183 cited documents.
- ☒ A check in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
Customer Number 21186

By: 
Atty: Timothy B. Clise
Reg. No. 40,957

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A. Customer Number 21186
(GENERAL)

S/N 09/483881

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner:	Ha Nguyen
Serial No.:	09/483881	Group Art Unit:	2812
Filed:	January 18, 2000	Docket:	303.672US1
Title:	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION		

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Supplemental Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants have included the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p). Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

12/17/2003 ZJU HAR1 00000044 09483881

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180.00 DP

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

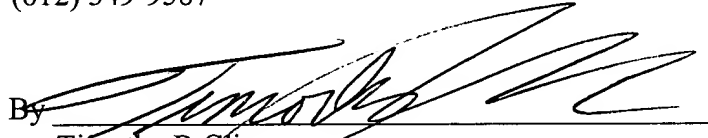
Respectfully submitted,

KIE Y. AHN ET AL.

By their Representatives,

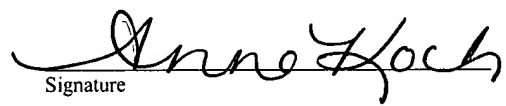
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
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Date 10 Dec '03

By 
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Anne Koch
Name


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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

(Use as many sheets as necessary)

Complete if Known

Application Number	09/483881
Filing Date	January 18, 2000
First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

Sheet 1 of 7

Attorney Docket No: 303.672US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
	US-2001/0002333	05/31/2001	Huang, Chao-Yuan , et al.	438	637	03/29/1999
	US-2001/0054771	12/27/2001	Wark, J. M., et al.	257	786	08/23/01
	US-1,254,987	01/29/1918	Cooper, H. S			10/15/1917
	US-1,976,375	10/09/1934	Smith, J. K.	148	11.5	01/27/1931
	US-2,244,608	06/03/1941	Cooper, H. S.	75	138	02/09/1939
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	US-3,832,456	08/27/1974	Kobetz, Paul , et al.	423	645	10/18/1962
	US-3,932,226	01/13/1976	Klatskin, J. B., et al.	204	16	12/06/1974
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	US-4,857,481	08/15/1989	Tam, G. , et al.	437	182	03/14/1989

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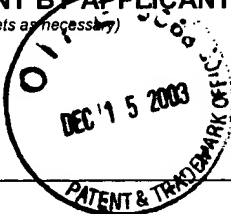
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Application Number	09/483881
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First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

Sheet 2 of 7

Attorney Docket No: 303.672US1

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	US-4,996,584	02/26/1991	Young, P. L., et al.	357	71	10/13/1988
	US-5,019,531	05/28/1991	Awaya, N. , et al.	437	180	05/19/1989
	US-5,045,635	09/02/1991	Kaplo, Joseph J., et al.	174	35 GC	06/16/1989
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	US-5,336,914	08/09/1994	Andoh, Takeshi	257	368	06/19/1992
	US-5,354,712	10/11/1994	Ho, Y. Q., et al.	437	195	11/12/1992
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EXAMINER

DATE CONSIDERED

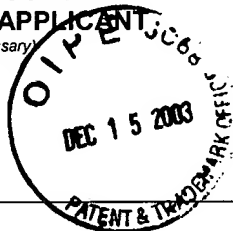
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Group Art Unit	2812
Examiner Name	Nguyen, Ha

Sheet 3 of 7

Attorney Docket No: 303.672US1

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EXAMINER

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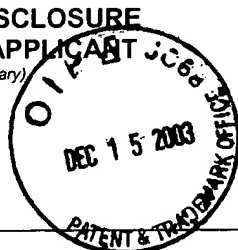
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First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

Sheet 4 of 7

Attorney Docket No: 303.672US1

	US-5,981,350	11/09/1999	Geusic, J. E., et al.	438	386	05/29/1998
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	US-6,004,884	12/21/1999	Abraham, L. C.	438	714	02/15/1996
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	US-6,015,738	01/18/2000	Levy, H. J., et al.	438	275	11/17/1997
	US-6,022,802	02/08/2000	Jang, Syun-Ming	438	656	03/18/1999
	US-6,025,261	02/15/2000	Farrar, C., et al.	438	619	04/29/1998
	US-6,030,877	02/29/2000	Lee, C., et al.	438	381	10/06/1997
	US-6,054,172	04/25/2000	Robinson, K., et al.	427	97	02/25/1999
	US-6,057,226	05/02/2000	Wong, L. D.	438	623	11/25/1997
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	US-6,075,278	06/13/2000	Farrar, P. A.	257	522	04/24/1997
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	US-6,091,136	07/18/2000	Jiang, T., et al.	257	676	11/17/1998
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	US-6,121,126	09/19/2000	Ahn, Kie, et al.	438	602	02/25/1998
	US-6,140,456	10/31/2000	Lee, Chung J., et al.	528	196	10/24/1997
	US-6,143,641	11/07/2000	Kitch, Vassili	438	618	01/26/2000
	US-6,159,842	12/12/2000	Chang, W., et al.	438	622	01/11/1999
	US-6,204,065	03/20/2001	Ochiai, T.	436	66	03/24/1998
	US-6,208,016	03/27/2001	Farrar, Paul	257	643	02/24/1999
	US-6,211,561	04/03/2001	Zhao, B	257	522	11/16/1998
	US-6,214,719	04/10/2001	Nag, Somnath	438	619	09/30/1999
	US-6,218,282	04/17/2001	Buynoski, M. S.	438	619	02/18/1999
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	US-6,288,905	09/11/2001	Chung, K. K.	361	771	10/04/1999
	US-6,323,543	11/27/2001	Jiang, T., et al.	257	676	04/13/2000
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	US-6,383,920	05/07/2002	Wang, P., et al.	438	639	01/10/2001
	US-6,563,219	05/13/2003	Ireland, Phillip, et al.	257	758	11/02/2001

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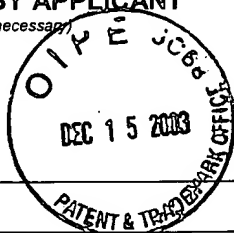
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Sheet 5 of 7

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FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
		ABE, K. , et al., "Sub-half Micron Copper Interconnects Using Reflow of Sputtered Copper Films", <u>VLSI Multilevel Interconnection Conference</u> , (June 25-27, 1995),308-311	
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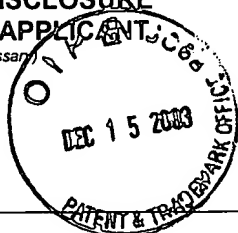
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Application Number	09/483881
Filing Date	January 18, 2000
First Named Inventor	Ahn, Kie
Group Art Unit	2812
Examiner Name	Nguyen, Ha

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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

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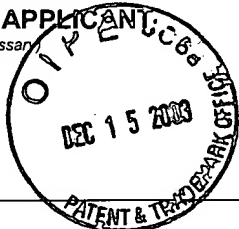
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